



Introduction

This application note is intended for hardware developers that are using the SPEAr600 embedded MPU in their target design.

The IBIS models are mandatory to run signal integrity simulation in the application PCB. PCB simulation is very important to make sure that the layout of the PCB does not introduce any functional problems or timing marginality in high speed interfaces like DDR2 and Ethernet.

The IBIS models provided for SPEAr600 are organized in a model library containing several models for each I/O pin (or for a functional group of I/Os). Each I/O pin or functional group of I/O has a set of models; each model corresponds to a certain operating mode of the I/O pads.

The operating modes are programmable and are defined by a proper setting of two registers, one in the miscellaneous register block and the other one in the memory controller block of the SPEAr600 device (for more details please refer to the miscellaneous registers and memory controller sections of the SPEAr600 user manual).

This document explains how to select the correct model from the library sp600_v13.ibs after reading the register settings or knowing the operating mode from the SPEAr600 user manual.

Note: *The registers referred to in this document are described in detail in the SPEAr600 user manual.*

1 PL_CLK & PL_GPIO IBIS model selection

The I/O signals of the PL_CLK & PL_GPIO interface form two main groups. Please refer to the following table for the I/O signals and the associated model name.

Table 1. Relation between the PL_.... block signals and the used model

PL_.... block signal name	IBIS model group name
PL_CLK[4:1]	PL_CLK
PL_GPIO[83:0]	PL_GPIO

2 GMAC IBIS model selection

The I/O signals of the GMAC interface form two main groups. Please refer to the following table for the I/O signals and the associated model name.

Table 2. Relation between the GMAC block signals and the used model

GMAC block signal name	IBIS model group name
GMII_TXCLK GMII_TXCLK125 MII_TXCLK TXD_0 TXD_1 TXD_2 TXD_3 GMII_TXD_4 GMII_TXD_5 GMII_TXD_6 GMII_TXD_7 TX_ER TX_EN RX_ER RX_DV RX_CLK RXD_0 RXD_1 RXD_2 RXD_3 GMII_RXD_4 GMII_RXD_5 GMII_RXD_7 GMII_RXD_6 COL CRS	GMAC_HF
MDIO MDC	GMAC_LF

3 SMI IBIS model selection

The I/O signals of the SMI interface form two main groups. Please refer to the following table for the SMI interface I/O signals and the associated model name.

Table 3. Relation between the SMI block signals and the used model

SMI block signal name	IBIS model group name
SMI_CLK SMIDATAIN SMIDATAOUT SMICS_0 SMICS_1	PL_GPIO

4 LVDS IBIS model selection

The I/O signals of the LVDS interface form two main groups. Please refer to the following table for the I/O signals and the associated model name.

Table 4. Relation between the LVDS block signals and the used model

LVDS block signal name	IBIS model group name
PH0 PH0n PH1 PH1n PH2 PH2n PH3 PH3n PH4 PH4n PH5 PH5n PH6 PH6n PH7 PH7n	LVDS_OUT
PH8 PH8n	LVDS_IN

5 DDR IBIS model selection

The I/O signals of the DDR interface form three main groups. Each group has one set of models associated.

Please refer to the following table for the I/O signals and the associated model names.

Table 5. Relation between the DDR block signals and the used model

DDR block signal name	IBIS model group name
DDR_CLKP & DDR_CLKN DDR_DQS_0 & DDR_nDQS_0 DDR_DQS_1 & DDR_nDQS_1	DDR_DIFF_[b7:b0] = DDR_DIFF_xxxxxxx
DDR_ADD[14,12,10,8,6,4,2,0] DDR_DATA[15,13,11,9,6,4,2,0] DDR_GATE_0 DDR_DM_1 DDR_CLKEN DDR_CS_1 DDR_ODT_1 DDR_BA_1 DDR_CAS	DDR_G_SIG_[b7:b3 & b1:b0] = DDR_G_SIG_xxxxxx See Note ⁽¹⁾
DDR_ADD[13,11,9,7,5,3,1] DDR_DATA[14,12,10,8,7,5,3,1] DDR_GATE_1 DDR_DM_0 DDR_CS_0 DDR_ODT_0 DDR_BA_0 DDR_BA_2 DDR_RAS DDR_WE	DDR_V_SIG_[b7:b3 & b1:b0] = DDR_V_SIG_xxxxxx See Note ⁽¹⁾

1. The b2 bit is not present.

Each model group name contains a set of models depending upon the value of the 8 bits [b7:b0] for DDR_DIFF and 7 bits [b7:b3 & b1:b0] for DDR_G_SIG and DDR_V_SIG.

In order to determine the value of these 7 or 8 bits, refer to the user manual of the SPEAr600 device for the following register names:

- SSTLPAD_CFG_CTR
- MEM11_CTL

The correlation between bits 0-8 (or 0-7) of the model group names and the bits of each register is given below:

- Register SSTLPAD_CFG_CTR (Address 0xFCA800F0).
 - b7 = SSTLPAD_CFG_CTR [15] = dram_type (1 = DDR2 interface)
 - b6 = SSTLPAD_CFG_CTR [3] = drive_mode_s_w (1 = Weak drive strength)
 - b5 = SSTLPAD_CFG_CTR [2] = prog_a (slope of the signals. 00 = slower slope)
 - b4 = SSTLPAD_CFG_CTR [1] = prog_b (slope of the signals. 11 = higher slope)
 - b3 = Internal level forced to zero.
 - b2 = Two cases:
 - Internal level forced to zero for CLKP or CLKN signals.
 - SSTLPAD_CFG_CTR [12] = pseudo_dif_
 - This is the bit register value for the signals DQS & nDQS (0 = diff. sig.).
- Register MEM11_CTL [1:0] (Address 0xFC60002C) = rtt_pad_terminat[1:0].

The following table is for the DQS, nDQS and DQ signals only. For all the other signals b1 = b0 = 0 (no ODT).

Table 6. DQS, nDQS and DQ on die termination (ODT)

MEM11_CTL [1]	MEM11_CTL [0]	B1	B0	Description
0	0	0	-	ODT disabled
0	1	1	1	ODT= 75 Ohm
1	0	1	0	ODT = 150 Ohm
1	1			Reserved

Note: “-“ means “don’t care”.

5.1 Example

The setting of the registers SSTLPAD_CFG_CTR and MEM11_CTL is normally done at each system boot-up by the XLOADER part of the boot code.

Let’s assume, as an example, that at the end of the boot operation the application reads these two registers and finds the following values:

- Register SSTLPAD_CFG_CTR (Address 0xFCA800F0) = 0x0000EAAD.
- Register MEM11_CTL Register (Address 0xFC60002C) = 0x03000002.

The correct model to be selected from the library with the above values is the following:

Table 7. Example of relation between DDR block signals and the used model

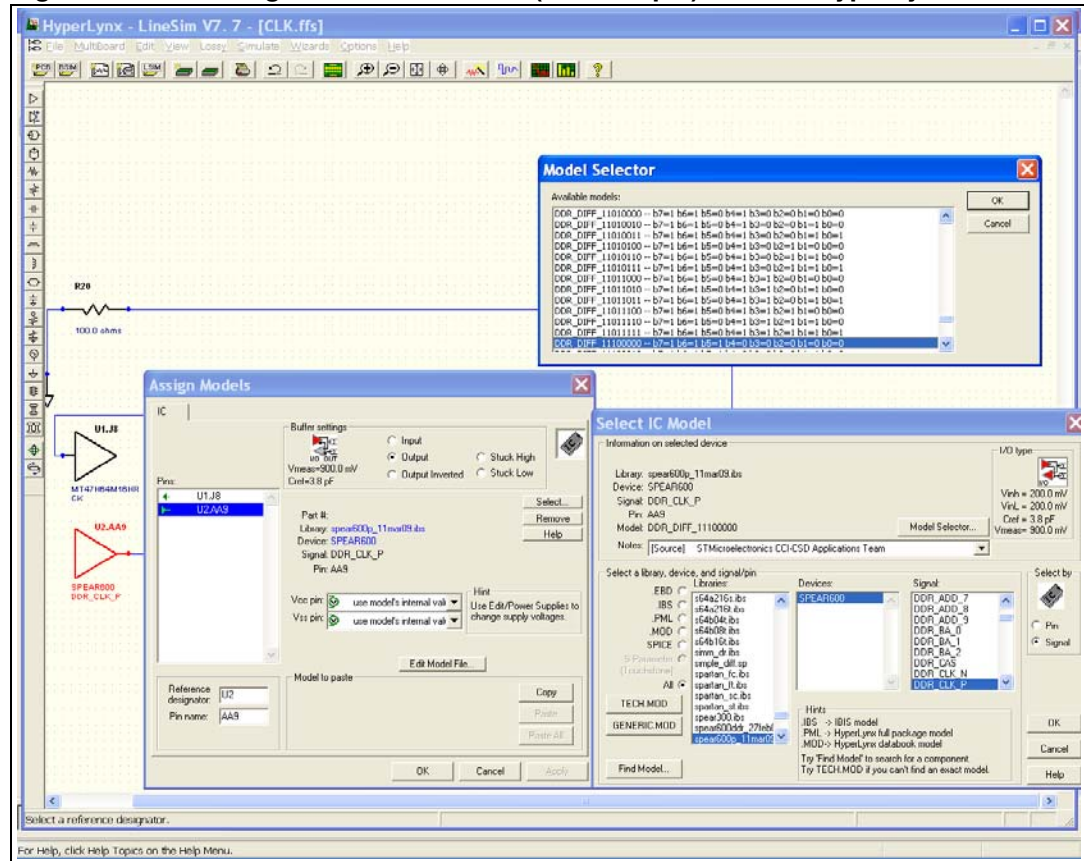
DDR block signal name	IBIS model used for application board
DDR_CLKP & DDR_CLKN	DDR_DIFF_[b7:b0] = DDR_DIFF_11100000
DDR_DQS_0 & nDDR_DQS_0 DDR_DQS_1 & nDDR_DQS_1	If READ => DDR_DIFF_[b7:b0] = DDR_DIFF_11100010 If WRITE => DDR_DIFF_[b7:b0] = DDR_DIFF_11100000

Table 7. Example of relation between DDR block signals and the used model (continued)

DDR block signal name	IBIS model used for application board
DDR_DATA[15,13,11,9,6,4,2,0]	If READ => DDR_G_SIG_[b7:b3 & b1:b0] = DDR_G_SIG_1110010 If WRITE => DDR_G_SIG_[b7:b3 & b1:b0] = DDR_G_SIG_1110000
DDR_ADD[14,12,10,8,6,4,2,0] DDR_GATE_0 DDR_DM_1 DDR_CLKEN DDR_CS_1 DDR_ODT_1 DDR_BA_1 DDR_CAS	DDR_G_SIG_[b7:b3 & b1:b0] = DDR_G_SIG_1110000
DDR_DATA[14,12,10,8,7,5,3,1]	If READ => DDR_V_SIG_[b7:b3 & b1:b0] = DDR_V_SIG_1110010 If WRITE => DDR_V_SIG_[b7:b3 & b1:b0] = DDR_V_SIG_1110000
DDR_ADD[13,11,9,7,5,3,1] DDR_GATE_1 DDR_DM_0 DDR_CS_0 DDR_ODT_0 DDR_BA_0 DDR_BA_2 DDR_RAS DDR_WE	DDR_V_SIG_[b7:b3 & b1:b0] = DDR_V_SIG_1110000

Note: In **Bold** the fixed bx bit values for the STM DDR2 application board.

Figure 1. CLKP signal simulation case (for example) with the HyperLynx tool



As shown in the above picture, if the simulation tool supports the model selector function, it's pretty easy to select the right model. When you select the pin name of the package (ball name) to be used in the simulation, the tool points automatically to the signal name and shows the model group name, listing in a window all the models contained in the group. As you can see in the model selector windows, all the models with all the available combination of the 7 or 8 bits are presented.

Knowing the operational mode or the content of the two registers explained in the previous paragraph, you can select the right model to be used by the simulation. In this specific example, the selected model is DDR_DIFF_11100000

There are simulation tools that do not support the model selector function. In this case, you must probably manually remove from the IBIS model library all the models with the bit settings that are not used in the simulation, only leaving in the library the models with the combination of bits related to the used operating mode.

6 USB IBIS model selection

All the I/O signals of the USB interface are grouped in one main group.

Please refer to the following table for the I/O signals and the associated model names.

Table 8. Relation between the USB block signals and the used model

USB block signal name	IBIS model group name
USB_DEVICE_DM	
USB_DEVICE_DP	
USB_HOST2_DM	usb2phy_p3_tx (if transmitter)
USB_HOST2_DP	usb2phy_p3_rx (if receiver)
USB_HOST1_DM	
USB_HOST1_DP	

7 Revision history

Table 9. Document revision history

Date	Revision	Changes
04-Dec-2009	1	Initial release.

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